



Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from,Europe,America and south Asia,supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of "Quality Parts,Customers Priority,Honest Operation,and Considerate Service",our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip,ALPS,ROHM,Xilinx,Pulse,ON,Everlight and Freescale. Main products comprise IC,Modules,Potentiometer,IC Socket,Relay,Connector.Our parts cover such applications as commercial,industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



Contact us

Tel: +86-755-8981 8866 Fax: +86-755-8427 6832

Email & Skype: info@chipsmall.com Web: www.chipsmall.com

Address: A1208, Overseas Decoration Building, #122 Zhenhua RD., Futian, Shenzhen, China



NOTES:

1. MATERIALS

HOUSING - HIGH TEMP. NYLON GLASS FILLED, UL 94V-0

COLOR: BLACK

EJECTOR - HIGH TEMP. NYLON GLASS FILLED, UL 94V-0

COLOR: SEE TABLE

TERMINAL - COPPER ALLOY

2. PLATING - SEE TABLE IN SHEET 5 & 6.

3. CARD SLOT ACCEPTS 1.27±0.10 MM MODULE THICKNESS.

(MEASURED OVER P.C. PADS)

4. RECOMMENDED MODULE LAYOUT SHALL BE AS PER JEDEC MO-237.

5. REFER TO PRODUCT SPEC. PS-87705-002 FOR PERFORMANCE SPECIFICATIONS.

6. PRODUCT SHALL BE PACKED IN TRAY.

7. PRODUCT SHALL HAVE DATE CODE STAMPED ON SIDE OF HOUSING.

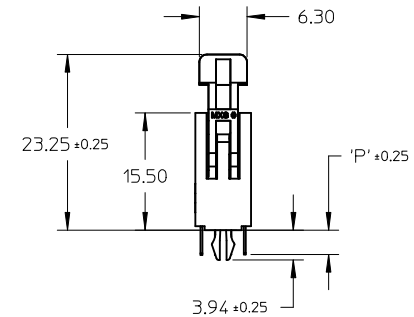
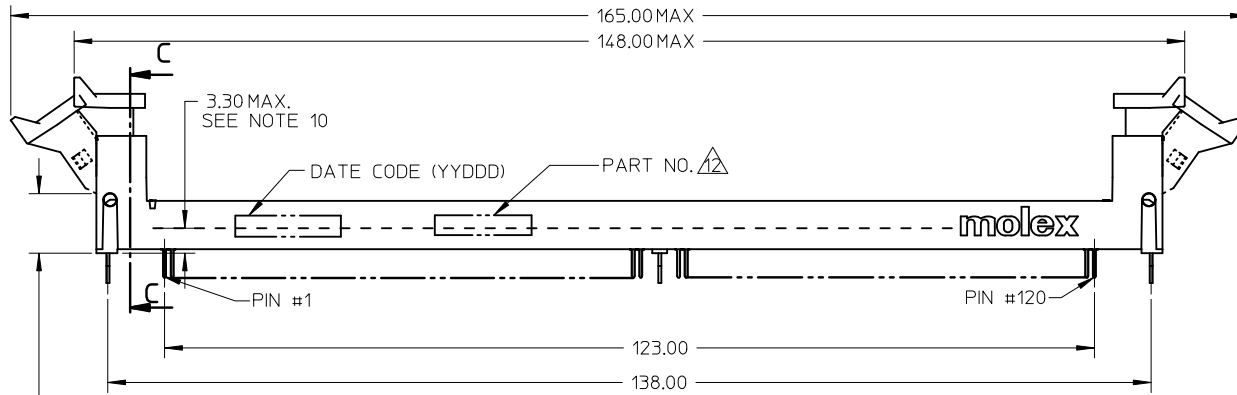
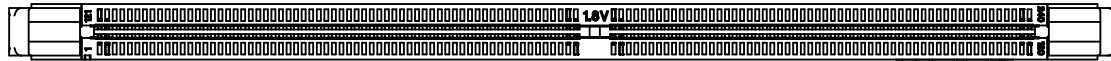
8. KEEP OUT AREA IS THE AREA WHERE THE CONNECTOR IS MOUNTED ONTO THE PCB WHICH DOES NOT INCLUDE THE LATCH.

9. REFER TO CRITICAL JEDEC INFORMATION FOR SOCKET OUTLINE PER SO-001.

10. DIMM MODULE SEATING PLANE FROM TOP OF PCB.

11. CONTACT MOLEX FOR AVAILABILITY OF PRODUCT OPTIONS.

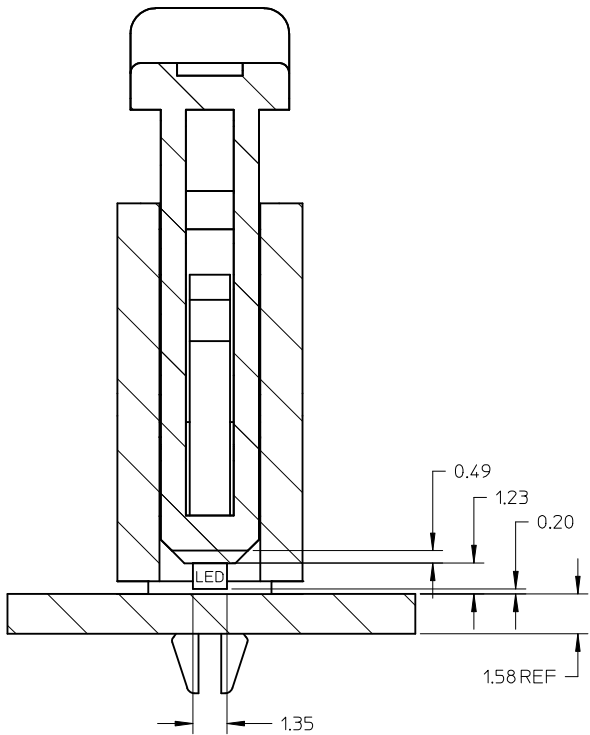
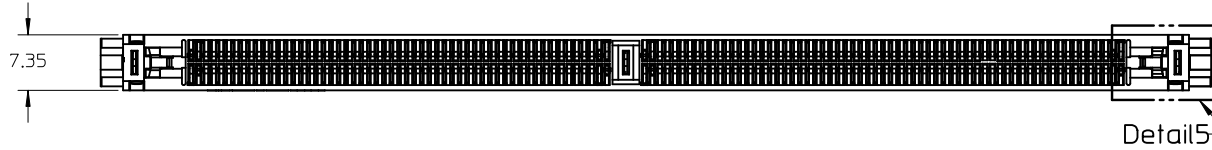
▲ PART NUMBER SHALL BE MARKED LEGIBLY AS 87705-****



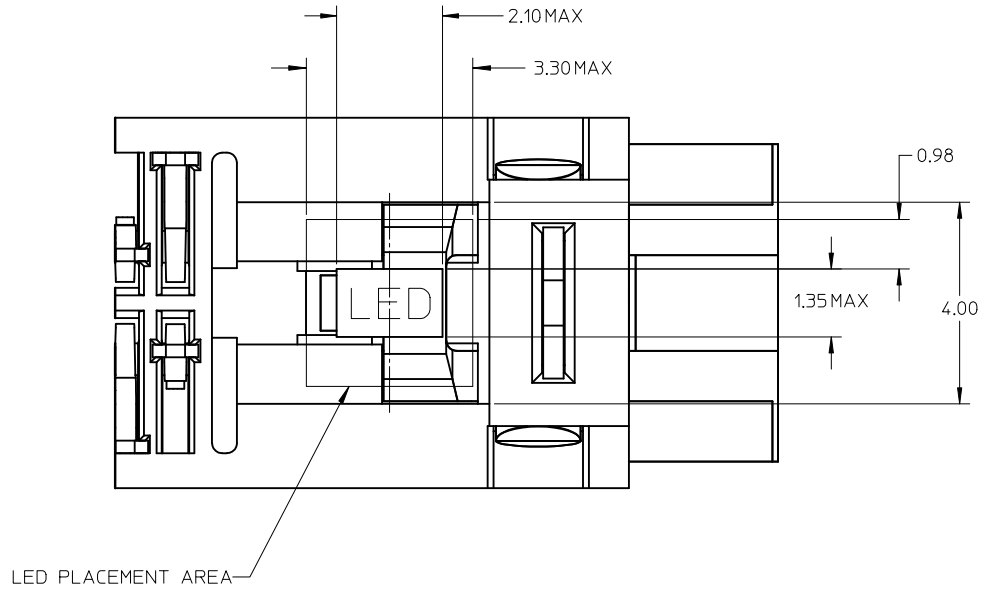
5.00 MIN
LATCH KEEP
OUT AREA

ADDED OPTION EC NO: S2012-0025 DRWN: CTEH CHKD: CGTAN APPR: SILENI 2009/11/16 2011/07/14 2011/07/14	QUALITY SYMBOLS $F_A=0$ $F_C=0$ $F_P=0$	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE		SCALE	DESIGN UNITS	THIRD ANGLE PROJECTION			
				MM ONLY		NTS	METRIC				
				mm	INCH	DRAWN BY	DATE	TITLE			
						CGOH	2002/05/09	DDR2 DIMM, 100MM PITCH			
D2	DESCRIPTION REV	4 PLACES ± --- ± ---		CHECKED BY		DATE					
		3 PLACES ± --- ± ---		DSOH		2002/07/22					
		2 PLACES ± 0.20 ± ---		APPROVED BY		DATE					
		1 PLACE ± --- ± ---		SKTOH		2002/07/23					
		ANGULAR ± 5 °		MATERIAL NO.		DOCUMENT NO.		SHEET NO.			
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		SEE TABLE		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION		SD-87705-001		1 OF 6			

10 9 8 7 6 5 4 3 2 1



SECTION C-C



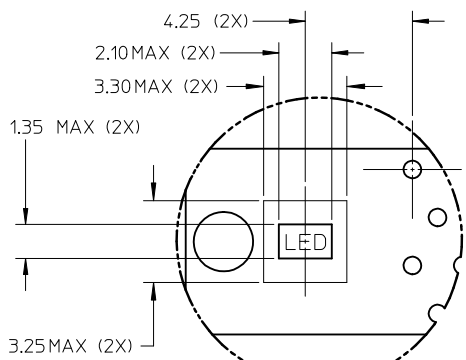
LED PLACEMENT AREA

Detail 5

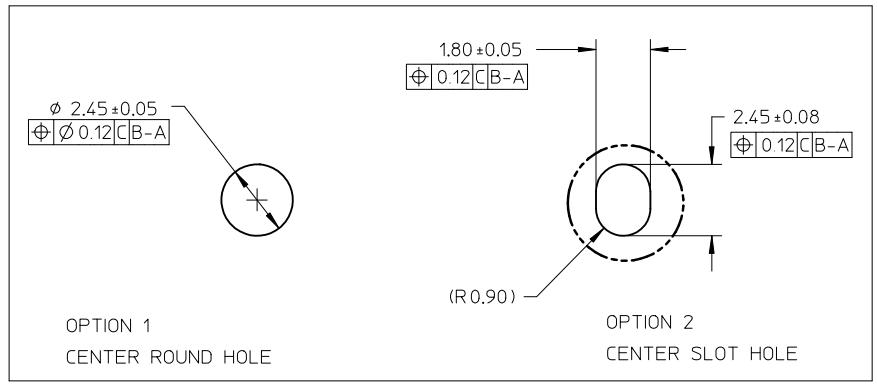
ADDED OPTION EC NO: S2012-0025 DRWN: CTEH CHKD: CGTAN APPR: SILENI	2009/11/16 2011/07/14 2011/07/14	DESCRIPTION REV	QUALITY SYMBOLS	GENERAL TOLERANCES (UNLESS SPECIFIED)	DIMENSION STYLE	SCALE	DESIGN UNITS	THIRD ANGLE PROJECTION
			$\nabla_A = 0$ $\nabla_C = 0$ $\nabla_P = 0$	mm INCH 4 PLACES ± --- ± --- 3 PLACES ± --- ± --- 2 PLACES ± 0.20 ± --- 1 PLACE ± --- ± --- ANGULAR ± 5 °	MM ONLY	NTS	METRIC	
				DRAWN BY: CGOH DATE: 2002/05/09 CHECKED BY: DS0H DATE: 2002/07/22 APPROVED BY: SKTOH DATE: 2002/07/23	TITLE	DDR2 DIMM, 100MM PITCH 240 CKTS (FORKLOCK VERSION)		
				MATERIAL NO. DOCUMENT NO. SHEET NO. SEE TABLE SD-87705-001 2 OF 6	MOLEX INCORPORATED THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION			

9 8 7 6 5 4 3 2 1

10 9 8 7 6 5 4 3 2 1

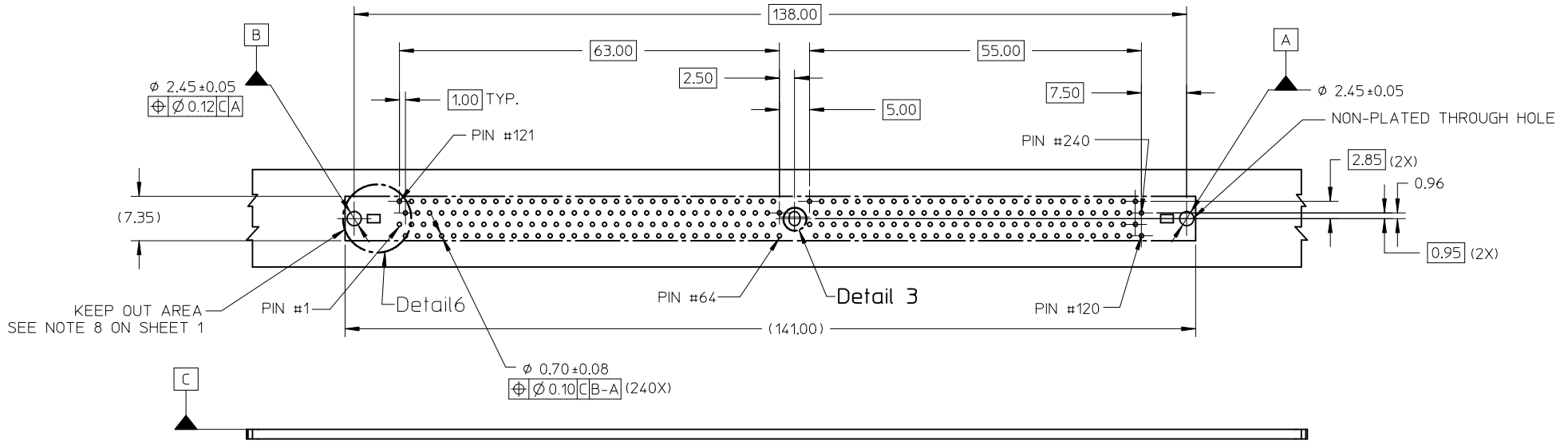


Detail 6



Detail 3

(SEE RECOMMENDED THICKNESS IN TABLE)
RECOMMENDED PCB LAYOUT
CONNECTOR SIDE



9 8 7 6 5 4 3 2 1

ADDED OPTION EC NO: S2012-0025 DRWN: CTEH 2009/11/16 CHKD: CGTAN 2011/07/14 APPR: SILENI 2011/07/14	QUALITY SYMBOLS $F_A=0$ $F_C=0$ $F_P=0$	GENERAL TOLERANCES (UNLESS SPECIFIED) mm INCH 4 PLACES ± --- ± --- 3 PLACES ± --- ± --- 2 PLACES ± 0.20 ± --- 1 PLACE ± --- ± --- ANGULAR ± 5 °	DIMENSION STYLE MM ONLY DRAWN BY: CGOH DATE: 2002/05/09 CHECKED BY: DSOH DATE: 2002/07/22 APPROVED BY: SKTOH DATE: 2002/07/23	SCALE: NTS DESIGN UNITS: METRIC THIRD ANGLE PROJECTION	TITLE: DDR2 DIMM, 100MM PITCH 240 CKTS (FORKLOCK VERSION) MOLEX INCORPORATED	
	DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS	MATERIAL NO.: SEE TABLE DOCUMENT NO.: SD-87705-001 SHEET NO.: 4 OF 6	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION			
	D2	REV	SIZE: A3			
	SEE TABLE					

PART NO.	KEY POS.	DIM 'P'	RECOMMENDED PCB THICKNESS	PLATING OPTION	LATCH COLOR	LUBRICATION
87705-0021	CENTER (1.8V)	2.67	1.57	0.38uM / 15 uIN MIN. GOLD ON CONTACT, 2.54uM/ 100uIN MIN. TIN ON SOLDERTAILS, 1.27uM/ 50uIN MIN. NICKEL UNDERPLATE	NATURAL	NO
87705-1021		3.18	2.36			
87705-1053		3.66				
87705-0031		2.67	1.57	0.03uM / 1 uIN MIN. GOLD ON CONTACT, 2.54uM/ 100uIN MIN. TIN ON SOLDERTAILS, 1.27uM/ 50uIN MIN. NICKEL UNDERPLATE		
87705-1031		3.18	2.36			
87705-0051		2.67	1.57	0.76uM / 30 uIN MIN. GOLD ON CONTACT, 2.54uM/ 100uIN MIN. TIN ON SOLDERTAILS, 1.27uM/ 50uIN MIN. NICKEL UNDERPLATE		
87705-1051		3.18	2.36			
87705-3061						YES

ADDED OPTION EC NO: S2012-0025 2009/11/16 DRWN:CTEH 2011/07/14 CHKD:GTAN APPR:SHLENI 2011/07/14	QUALITY SYMBOLS	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE NTS	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION	
	$F_A=0$	mm	INCH	DRAWN BY CGOH	DATE 2002/05/09	TITLE DDR2 DIMM, 100MM PITCH			
	$F_G=0$	4 PLACES ± ---	± ---	CHECKED BY DSOH	DATE 2002/07/22	240 CKTS (FORKLOCK VERSION)			
	$F_P=0$	3 PLACES ± ---	± ---	APPROVED BY SKTOH	DATE 2002/07/23	MOLEX INCORPORATED			
		2 PLACES ± 0.20	± ---	MATERIAL NO. SEE TABLE		DOCUMENT NO. SD-87705-001		SHEET NO. 5 OF 6	
		1 PLACE ± ---	± ---	DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS					
		ANGULAR ± 5 °		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION					

PART NO.	KEY POS.	DIM 'P'	RECOMMENDED PCB THICKNESS	PLATING OPTION	LATCH COLOR
87705-5051	CENTER (1.8V)	2.67	1.57	0.76μM / 30 μIN MIN. GOLD ON CONTACT, 2.54μM/ 100μIN MIN. TIN ON SOLDERTAILS, 1.27μM/ 50μIN MIN. NICKEL UNDERPLATE	CLEAR
87705-5151		3.18	2.36		
87705-6151		3.18	2.36	0.38μM / 15 μIN MIN. GOLD ON CONTACT, 2.54μM/ 100μIN MIN. TIN ON SOLDERTAILS, 1.27μM/ 50μIN MIN. NICKEL UNDERPLATE	
87705-9101		2.67	1.57	0.38μM / 15 μIN MIN. GOLD ON CONTACT, 2.54μM/ 100μIN MIN. TIN ON SOLDERTAILS, 1.27μM/ 50μIN MIN. NICKEL UNDERPLATE	

ADDED OPTION EC NO: S2012-0025 2009/11/16 DRW: CTEH CHKD: CGTAN 2011/07/14 APPR: SILENI 2011/07/14	DESCRIPTION REV	QUALITY SYMBOLS	GENERAL TOLERANCES (UNLESS SPECIFIED)	DIMENSION STYLE	SCALE	DESIGN UNITS	THIRD ANGLE PROJECTION	
		$\nabla_A = 0$ $\nabla_C = 0$ $\nabla_P = 0$	mm INCH	MM ONLY	NTS	METRIC		
		4 PLACES ± --- ± --- 3 PLACES ± --- ± --- 2 PLACES ± 0.20 ± --- 1 PLACE ± --- ± ---	DRAWN BY: CGOH DATE: 2002/05/09 CHECKED BY: DSOH DATE: 2002/07/22 APPROVED BY: SKTOH DATE: 2002/07/23	TITLE		DDR2 DIMM, 100MM PITCH 240 CKTS (FORKLOCK VERSION)		
		ANGULAR ± 5 °	MATERIAL NO. SKTOH DOCUMENT NO. SD-87705-001 SHEET NO. 6 OF 6	MOLEX INCORPORATED 				
D2		DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS	SEE TABLE	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION				